

THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Certificate**

APR 04 2006

In re Application of:

Thomas S. Roche et al.

Application No.: 10/649,426

Filed: August 26, 2003

) Patent No.: 6,924,172 B2

) Issue Date: August 2, 2005

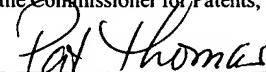
) Docket No.: SC1251ZP

Title: METHOD OF FORMING A BOND PAD INCLUDING REMOVING A PORTION  
OF A PROTECTIVE LAYER

Certificate of Mailing

Date of deposit: 3-27-06

I hereby certify that this paper is being deposited with the United States Postal Service on the date indicated above, as first-class mail, with sufficient postage attached thereto, in an envelope addressed to the Commissioner for Patents, Alexandria, VA 22313.



Signature of Person Mailing Paper

Pat Thomas

Printed Name of Person Mailing Paper

Certificate of Corrections Branch  
Commissioner for Patents  
Alexandria, VA 22313

**SUBMISSION OF CERTIFICATE OF CORRECTION**

Dear Commissioner:

Enclosed, in duplicate, is a Certificate of Correction for error in the subject patent. The amendment to the title of the invention, made at the examiner's request, is not included. Please enter this correction.

Since the error is on the part of the United States Patent Office, there should be no charge.

Respectfully submitted,



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March 26, 2006  
Date



**UNITED STATES PATENT AND TRADEMARK OFFICE  
CERTIFICATE OF CORRECTION**Page 1 of 1

PATENT NO.: **6,924,172 B2**  
APPLICATION NO: **10/649,426**  
DATE: **August 2, 2005**  
INVENTOR(S): **Thomas S. Roche et al.**

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

On First Page, Title of Invention (Item 54), change:

**“METHOD OF FORMING A BOND PAD”**

to

**-- METHOD OF FORMING A BOND PAD INCLUDING REMOVING A PORTION OF A  
PROTECTIVE LAYER--**

MAILING ADDRESS OF SENDER (Please do not use customer number below)

Freescale Semiconductor, Inc.

Law Department

7700 West Parmer Lane PL02

Austin, TX 78729

*AIR - 4 2006*

**UNITED STATES PATENT AND TRADEMARK OFFICE**  
**CERTIFICATE OF CORRECTION**Page 1 of 1

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